

Bill of Materials

TIDA 00258

TI DESIGNS

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	9	C15	0.1uF	Capacitor, Ceramic, 50V, X7R, 20%	Any			0603	
2	3	C12, C13, C14	100pF	Capacitor, Ceramic, 50V, X7R, 10%	Any			0603	
3	3	C5, C9, C10	1.0uF	Capacitor, Ceramic, 25V, X7R, 20%	Any			0805	
4	2	D1, D2	TL431CPK	IC, Adjustable precision shunt regulator	TI			SOT-89	
5	2	D3, D4	S1A-13-F	Diode, Glass Passivated Rect. 1A, 50V	Diodes			SMA	
6	1	J1	22-05-3041	Header, Friction Lock Ass'y, 4-pin Right Angle	Molex			0.400 x 0.500	
7	2	Q1, Q7	2SD1758TLR	Transistor, NPN Medium Power, 32V, 2A	Rohm			SC-63	
8	2	Q2, Q3	2SK3019	MOSFET, Nch, 30V, 100mA, 8 Ohm	Rohm			SC-75A	
9	2	Q4, Q5	Si1023X	MOSFET, Pch, -20V, 350mA, 1.2 Ohm	Vishay			SC-89	
10	1	Q6	Si4435DDY	MOSFET, Pch, 30V, 8.0A, 20 milliohm	Vishay			SOT23	
11	1	Q8	ZXMN3A14FTA	MOSFET, Nch, 30V, 3.2A, 65 milliohm	Diodes/Zetex			SOT23	
12	1	Q9	BSS223PW	MOSFET, Pch, -20V, -0.39A, 1.2 Ohm	Infineon			SOT323	
13	5	R1, R8, R9, R10, R11	1K	Resistor, Chip, 1/16W, 5%	Any			0603	
14	5	R12, R13, R21, R23, R25	100	Resistor, Chip, 1/16W, 5%	Any			0603	
15	5	R14, R15, R16, R17, R31	100	Resistor, Chip, 1/4W, 5%	Vishay			1206	
16	1	R18	.020 75ppm	Resistor, Chip, 1/2W, 1%, 75ppm	Dale			2010	
17	1	R19	3M	Resistor, Chip, 1/16W, 5%	Any			0603	
18	2	R2, R3	10	Resistor, Chip, 1W, 1%	Vishay/Dale			2010	
19	3	R20, R22, R24	200	Resistor, Chip, 1/16W, 5%	Any			0603	
20	1	R26	7.5	Resistor, Chip, 2W, 1%	Stackpole			2512	
21	2	R27, R28	8.2	Resistor, Chip, 1W, 1%	Panasonic - ECG			2512	
22	0	R29	DNP	Resistor, Chip, 1/16W, 5%	Any			0603	
23	1	R30	20K	Resistor, Chip, 1/16W, 5%	Any			0603	
24	1	R32	20K	Resistor, Chip, 1/16W, 1%	Any			0603	
25	1	R33	10K	Resistor, Chip, 1/16W, 1%	Any			0603	
26	1	R4	30.0K	Resistor, Chip, 1/16W, 1%	Any			0402	
27	1	R5	57.6K	Resistor, Chip, 1/16W, 1%	Any			0402	
28	1	R6	124K	Resistor, Chip, 1/16W, 1%	Any			0402	
29	1	R7	9.31K	Resistor, Chip, 1/16W, 1%	Any			0402	
30	1	RT1	10K	Thermistor, 10K Ohm	Semitec			0.095 x 0.150 inches	
31	4	TB1, TB2, TB3, TB4	ED555/3DS	Terminal Block, 3-pin, 6A, 3.5mm	OST			0.41 x 0.25 inch	
32	1	TP1	CHG+	Test Point, White, Thru Hole Color Keyed	Keystone			0.100 x 0.100 inch	
33	1	TP2	CHG-	Test Point, White, Thru Hole Color Keyed	Keystone			0.100 x 0.100 inch	
34	1	TP3	CHGFET	Test Point, White, Thru Hole Color Keyed	Keystone			0.100 x 0.100 inch	
35	1	TP4	2.7V	Test Point, White, Thru Hole Color Keyed	Keystone			0.100 x 0.100 inch	
36	1	TP5	GND	Test Point, White, Thru Hole Color Keyed	Keystone			0.100 x 0.100 inch	
37	1	U1	BQ33100PW	IC, SUPERCAP PACKMANAGER and PROTECTION	TI			TSSOP-24	
38	1	--	--	PCB	Any			2 x 3 inches	

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